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4. The delivering method according to claim 1,
wherein the step of inclining the target object
comprises the sub-steps of:

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moving upward at least one lift pin at a
predetermined speed so as to cause a part of the target

object to rise from the surface of the table, thereby introducing air into the clearance between the target object and the table; and

moving upward each of the lift pins at a speed higher than said predetermined speed so as to move upward the target object.

9. A table mechanism, comprising a table for performing the delivery of the target object to and from a transfer mechanism of the target object, and a plurality of lift pins for causing the target object on said table to rise from the table surface so as to support the target object, wherein at least one lift pin positioned on the side of the transfer mechanism is moved higher than the other lift pins such that the target object is supported by said lift pins in an inclined fashion.

10. A table mechanism for receiving the target object transferred by a transfer mechanism, for applying a predetermined processing to the received target object, and for delivering the processed target object onto the transfer mechanism, comprising:

a table having the target object disposed thereon and provided with a plurality of lift pins in an upper portion thereof, said lift pins being moved upward from within the table onto the outside of the table when receiving the target object transferred by said transfer mechanism and when delivering the processed

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wherein the target object to be processed is a semiconductor wafer, said predetermined processing is an inspection of the electrical characteristics of the integrated circuit formed on a semiconductor wafer, and said transfer mechanism is a pincette for transferring the semiconductor wafer.

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